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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	8064
Number of Logic Elements/Cells	-
Total RAM Bits	73728
Number of I/O	115
Number of Gates	500000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax500-2pq208

Axcelerator Family Device Status

Axcelerator® Devices	Status
AX125	Production
AX250	Production
AX500	Production
AX1000	Production
AX2000	Production

Temperature Grade Offerings

Package	AX125	AX250	AX500	AX1000	AX2000
PQ208	–	C, I, M	C, I, M	–	–
CQ208	–	M	M	–	–
CQ256	–	–	–	–	M
FG256	C, I	C, I, M	–	–	–
FG324	C, I	–	–	–	–
CQ352	–	M	M	M	M
FG484	–	C, I, M	C, I, M	C, I, M	–
CG624	–	–	–	M	M
FG676	–	–	C, I, M	C, I, M	–
BG729	–	–	–	C, I, M	–
FG896	–	–	–	C, I, M	C, I, M
FG1152	–	–	–	–	C, I, M

C = Commercial

I = Industrial

M = Military

Speed Grade and Temperature Grade Matrix

Temperature Grade	Std	–1	–2
C	✓	✓	✓
I	✓	✓	✓
M	✓	✓	–

C = Commercial

I = Industrial

M = Military

1 – General Description

Axcelerator devices offer high performance at densities of up to two million equivalent system gates. Based upon the Microsemi AX architecture, Axcelerator has several system-level features such as embedded SRAM (with complete FIFO control logic), PLLs, segmentable clocks, chip-wide highway routing, and carry logic.

Device Architecture

AX architecture, derived from the highly-successful SX-A sea-of-modules architecture, has been designed for high performance and total logic module utilization (Figure 1-1). Unlike in traditional FPGAs, the entire floor of the Axcelerator device is covered with a grid of logic modules, with virtually no chip area lost to interconnect elements or routing.

Programmable Interconnect Element

The Axcelerator family uses a patented metal-to-metal antifuse programmable interconnect element that resides between the upper two layers of metal (Figure 1-2 on page 1-2). This completely eliminates the channels of routing and interconnect resources between logic modules (as implemented on traditional FPGAs) and enables the efficient sea-of-modules architecture. The antifuses are normally open circuit and, when programmed, form a permanent, passive, low-impedance connection, leading to the fastest signal propagation in the industry. In addition, the extremely small size of these interconnect elements gives the Axcelerator family abundant routing resources.

The very nature of Microsemi's nonvolatile antifuse technology provides excellent protection against design pirating and cloning (FuseLock technology). Typical cloning attempts are impossible (even if the security fuse is left unprogrammed) as no bitstream or programming file is ever downloaded or stored in the device. Reverse engineering is virtually impossible due to the difficulty of trying to distinguish between programmed and unprogrammed antifuses and also due to the programming methodology of antifuse devices (see "Security" on page 2-108).

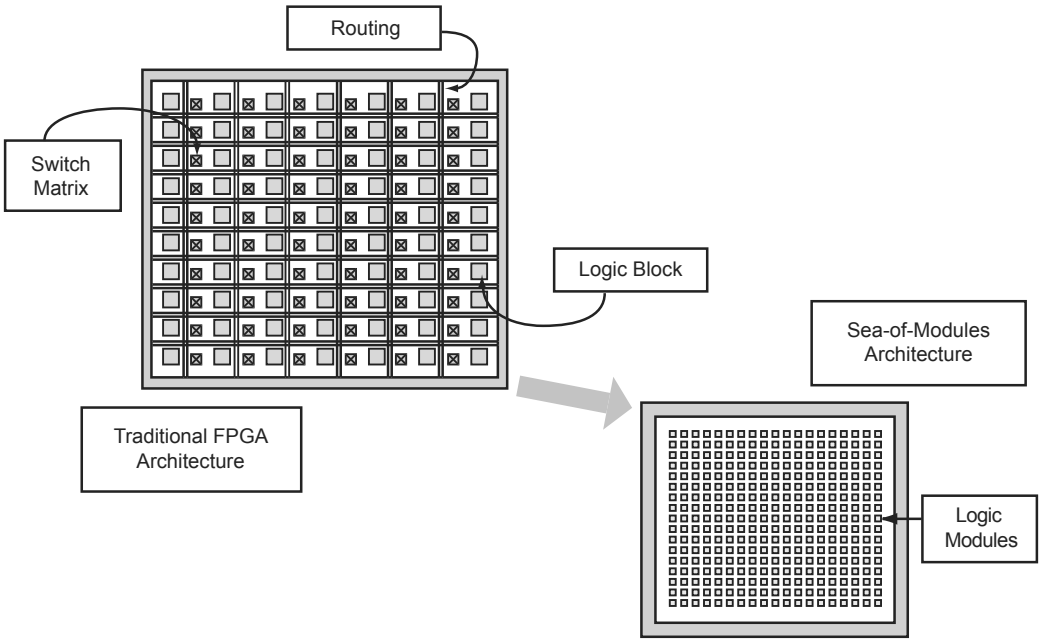

Figure 1-1 • **Sea-of-Modules Comparison**

Poutputs = PI/O * po * Fpo

C_{load} = the output load (technology dependent)
VCCI = the output voltage (technology dependent)
po = the number of outputs
F_{po} = the average output frequency

Pmemory = P11 * Nblock * FRCLK + P12 * Nblock * FWCLK

N_{block} = the number of RAM/FIFO blocks (1 block = 4k)
F_{RCLK} = the read-clock frequency of the memory
F_{WCLK} = the write-clock frequency of the memory

PPLL = P13 * FCLK

F_{RefCLK} = the clock frequency of the clock input of the PLL
F_{CLK} = the clock frequency of the first clock output of the PLL

Power Estimation Example

This example employs an AX1000 shift-register design with 1,080 R-cells, one C-cell, one reset input, and one LVTTL 12 mA output, with high slew.

This design uses one HCLK at 100 MHz.

ms = 1,080 (in a shift register - 100% of R-cells are toggling at each clock cycle)
Fs = 100 MHz
s = 1080
=> P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs = 79 mW
and Fs = 100 MHz
=> $P_{R\text{-}cells}$ = P7 * ms * Fs = 173 mW
mc = 1 (1 C-cell in this shift-register)
and Fs = 100 MHz
=> $P_{C\text{-}cells}$ = P8 * mc * Fs = 0.14 mW
F_{pi} ~ 0 MHz
and pi= 1 (1 reset input => this is why F_{pi}=0)
=> P_{inputs} = P9 * pi * F_{pi} = 0 mW
F_{po} = 50 MHz
and po = 1
=> $P_{outputs}$ = $P_{I/O}$ * po * F_{po}= 27.10 mW
No RAM/FIFO in this shift-register
=> P_{memory} = 0 mW
No PLL in this shift-register
=> P_{PLL} = 0 mW
$P_{ac} = P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$ = 276 mW
P_{dc} = 7.5mA * 1.5V = 11.25 mW
$P_{total} = P_{dc} + P_{ac}$ = 11.25 mW + 276mW = 290.30 mW

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

T_J = Junction Temperature = $\Delta T + T_a$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$\Delta T = \theta_{ja} * P$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. } (°C) - \text{Max. ambient temp. } (°C)}{\theta_{ja}(°C/W)} = \frac{125°C - 70°C}{13.6°C/W} = 4.04\ W$$

User-Defined Supply Pins

VREF **Supply Voltage**

Reference voltage for I/O banks. VREF pins are configured by the user from regular I/O pins; VREF pins are not in fixed locations. There can be one or more VREF pins in an I/O bank.

Global Pins

HCLKA/B/C/D **Dedicated (Hardwired) Clocks A, B, C and D**

These pins are the clock inputs for sequential modules or north PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. This input is directly wired to each R-cell and offers clock speeds independent of the number of R-cells being driven. When the HCLK pins are unused, it is recommended that they are tied to ground.

CLKE/F/G/H **Routed Clocks E, F, G, and H**

These pins are clock inputs for clock distribution networks or south PLLs. Input levels are compatible with all supported I/O standards. There is a P/N pin pair for support of differential I/O standards. Single-ended clock I/Os can only be assigned to the P side of a paired I/O. The clock input is buffered prior to clocking the R-cells. When the CLK pins are unused, Microsemi recommends that they are tied to ground.

JTAG/Probe Pins

PRA/B/C/D **Probe A, B, C and D**

The Probe pins are used to output data from any user-defined design node within the device (controlled with Silicon Explorer II). These independent diagnostic pins can be used to allow real-time diagnostic output of any signal path within the device. The pins' probe capabilities can be permanently disabled to protect programmed design confidentiality. The probe pins are of LVTTL output levels.

TCK **Test Clock**

Test clock input for JTAG boundary-scan testing and diagnostic probe (Silicon Explorer II).

TDI **Test Data Input**

Serial input for JTAG boundary-scan testing and diagnostic probe. TDI is equipped with an internal 10 kΩ pull-up resistor.

TDO **Test Data Output**

Serial output for JTAG boundary-scan testing.

TMS **Test Mode Select**

The TMS pin controls the use of the IEEE 1149.1 boundary-scan pins (TCK, TDI, TDO, TRST). TMS is equipped with an internal 10 kΩ pull-up resistor.

TRST **Boundary Scan Reset Pin**

The TRST pin functions as an active-low input to asynchronously initialize or reset the boundary scan circuit. The TRST pin is equipped with a 10 kΩ pull-up resistor.

Special Functions

LP **Low Power Pin**

The LP pin controls the low power mode of Axcelerator devices. The device is placed in the low power mode by connecting the LP pin to logic high. To exit the low power mode, the LP pin must be set Low. Additionally, the LP pin must be set Low during chip powering-up or chip powering-down operations. See "Low Power Mode" on page 2-106 for more details.

NC **No Connection**

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

Timing Characteristics

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 1 (8 mA) / Low Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		14.28		16.27		19.13	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		15.25		17.37		20.42	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		14.26		16.24		19.09	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.56		1.57		1.58	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		1.95		1.96		1.97	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		039		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 4 (24mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		2.99		3.41		4.01	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.49		2.51		2.51	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.59		2.95		3.46	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		3.56		4.06		4.77	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Class II

Table 2-47 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min,. V	mA	mA
-0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.8	VREF + 0.8	15.2	-15.2

AC Loadings

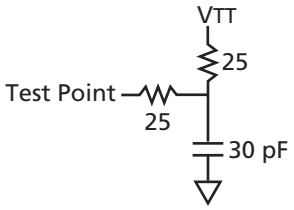

Figure 2-22 • AC Test Loads

Table 2-48 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.75	VREF + 0.75	VREF	1.25	30

*Note: * Measuring Point = V_{trip}*

Timing Characteristics

Table 2-49 • 2.5 V SSTL2 Class II I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
2.5 V SSTL2 Class II I/O Module Timing								
t_{DP}	Input Buffer		1.89		2.16		2.53	ns
t_{PY}	Output Buffer		2.39		2.72		3.20	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Global Resource Distribution

At the root of each global resource is a PLL. There are two groups of four PLLs for every device. One group, located at the center of the north edge (in the I/O ring) of the chip, sources the four HCLKs. The second group, located at the center of the south edge (again in the I/O ring), sources the four CLKs (Figure 2-38).

Regardless of the type of global resource, HCLK or CLK, each of the eight resources reach the ClockTileDist (CTD) Cluster located at the center of every core tile with zero skew. From the ClockTileDist Cluster, all four HCLKs and four CLKs are distributed through the core tile (Figure 2-39).

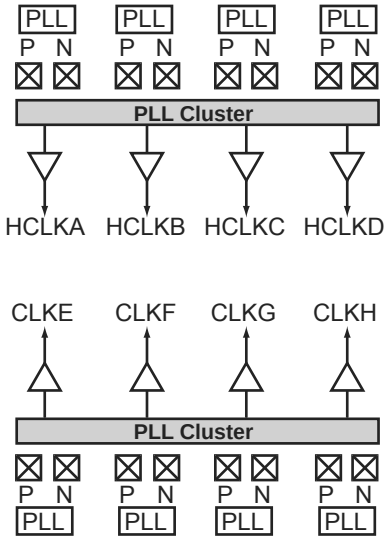

Figure 2-38 • **PLL Group**

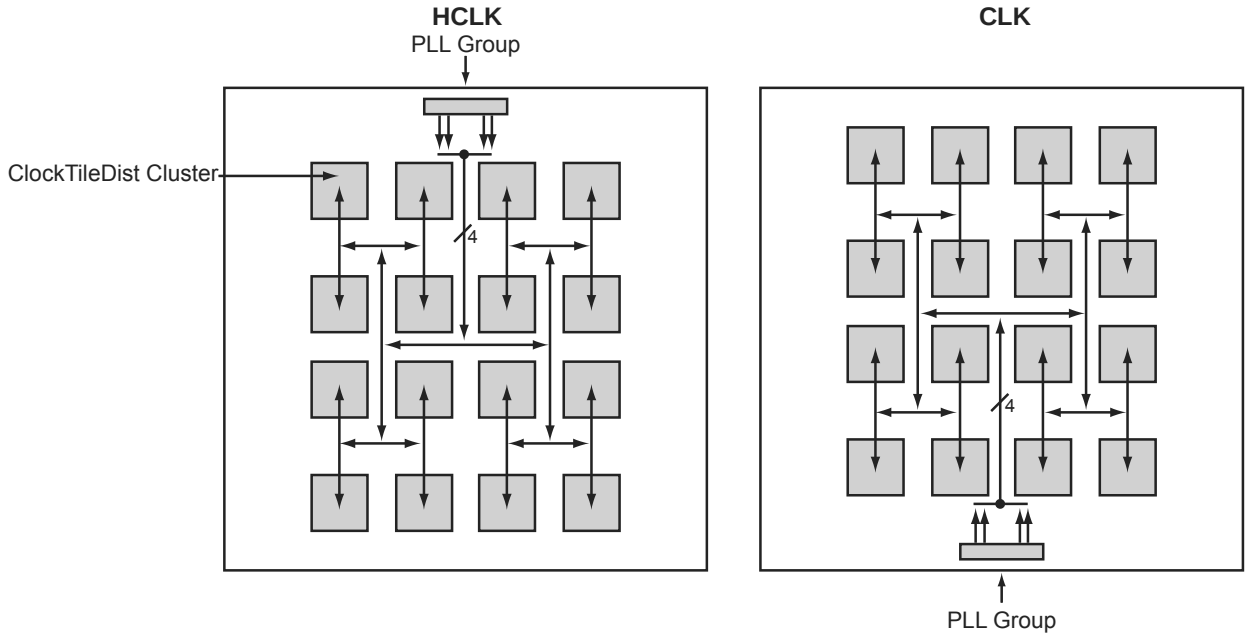

Figure 2-39 • **Example of HCLK and CLK Distributions on the AX2000**

***Table 2-90* • Two RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t_{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t_{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

FIFO

Every memory block has its own embedded FIFO controller. Each FIFO block has one read port and one write port. This embedded FIFO controller uses no internal FPGA logic and features:

- Glitch-free FIFO Flags
- Gray-code address counters/pointers to prevent metastability problems
- Overflow and underflow control

Both ports are configurable in various sizes from 4k x 1 to 128 x 36, similar to the RAM block size. Each port is fully synchronous.

Read and write operations can be completely independent. Data on the appropriate WD pins are written to the FIFO on every active WCLK edge as long as WEN is high. Data is read from the FIFO and output on the appropriate RD pins on every active RCLK edge as long as REN is asserted.

The FIFO block offers programmable almost-empty (AEMPTY) and almost-full (AFULL) flags as well as EMPTY and FULL flags (Figure 2-61):

- The FULL flag is synchronous to WCLK. It allows the FIFO to inhibit writing when full.
- The EMPTY flag is synchronous to RCLK. It allows the FIFO to inhibit reading at the empty condition.

Gray code counters are used to prevent metastability problems associated with flag logic. The depth of the FIFO is dependent on the data width and the number of memory blocks used to create the FIFO. The write operations to the FIFO are synchronous with respect to the WCLK, and the read operations are synchronous with respect to the RCLK.

The FIFO block may be reset to the empty state.

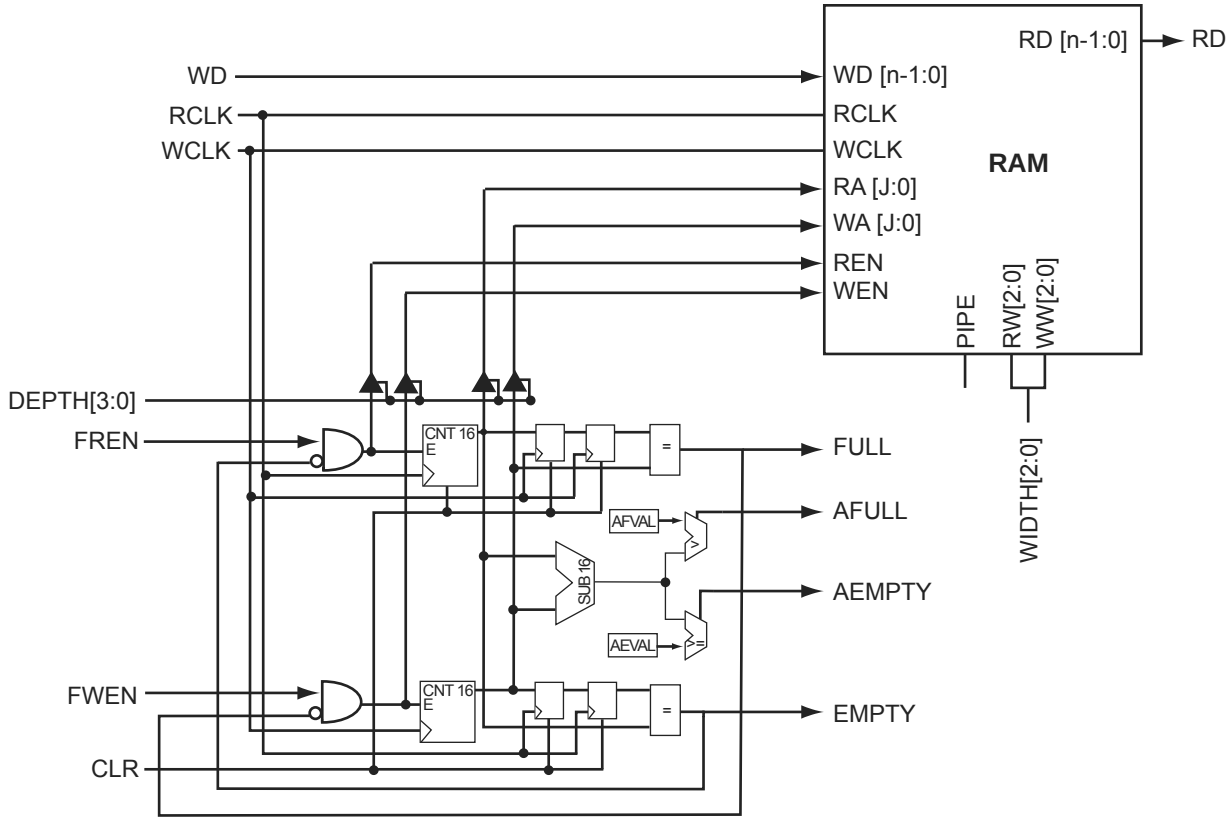

Figure 2-61 • **Axcelerator RAM with Embedded FIFO Controller**

FG484	
AX250 Function	**Pin Number**
Bank 0	
IO00NB0F0	D7
IO00PB0F0	D6
IO01NB0F0	E7
IO01PB0F0	E6
IO02NB0F0	C5
IO02PB0F0	C4
IO03NB0F0	C7
IO03PB0F0	C6
IO04NB0F0	E9
IO04PB0F0	E8
IO05NB0F0	D9
IO05PB0F0	D8
IO06NB0F0	B7
IO06PB0F0	B6
IO07NB0F0	C9
IO07PB0F0	C8
IO08NB0F0	A7
IO08PB0F0	A6
IO09NB0F0	B9
IO09PB0F0	B8
IO10NB0F0	A9
IO10PB0F0	A8
IO11NB0F0	B10
IO11PB0F0	A10
IO12NB0F0/HCLKAN	E11
IO12PB0F0/HCLKAP	E10
IO13NB0F0/HCLKBN	D12
IO13PB0F0/HCLKBP	D11
Bank 1	
IO14NB1F1/HCLKCN	F13
IO14PB1F1/HCLKCP	F12
IO15NB1F1/HCLKDN	E14
IO15PB1F1/HCLKDP	E13
IO16NB1F1	C13
IO16PB1F1	C12

FG484	
AX250 Function	**Pin Number**
IO17NB1F1	B14
IO17PB1F1	B13
IO18NB1F1	A14
IO18PB1F1	A13
IO19NB1F1	A16
IO19PB1F1	A15
IO20NB1F1	B16
IO20PB1F1	B15
IO21NB1F1	C17
IO21PB1F1	C16
IO22NB1F1	F15
IO22PB1F1	F14
IO23NB1F1	D16
IO23PB1F1	D15
IO24NB1F1	E16
IO24PB1F1	E15
IO25NB1F1	F18
IO25PB1F1	F17
IO26NB1F1	D18
IO26PB1F1	E17
IO27NB1F1	G16
IO27PB1F1	G15
Bank 2	
IO28NB2F2	F19
IO28PB2F2	E19
IO29NB2F2	J16
IO29PB2F2	H16
IO30NB2F2	E20
IO30PB2F2	D20
IO31NB2F2	J17
IO31PB2F2	H17
IO32NB2F2	G20
IO32PB2F2	F20
IO33NB2F2	H19
IO33PB2F2	G19
IO34NB2F2	E22

FG484	
AX250 Function	**Pin Number**
IO34PB2F2	D22
IO35NB2F2	J18
IO35PB2F2	H18
IO36NB2F2	G21
IO36PB2F2	F21
IO37NB2F2	K19
IO37PB2F2	J19
IO38NB2F2	J20
IO38PB2F2	H20
IO39NB2F2	L16
IO39PB2F2	K16
IO40NB2F2	J21
IO40PB2F2	H21
IO41NB2F2	L17
IO41PB2F2	K17
IO42NB2F2	J22
IO42PB2F2	H22
IO43NB2F2	L18
IO43PB2F2	K18
IO44NB2F2	L20
IO44PB2F2	K20
Bank 3	
IO45NB3F3	M19
IO45PB3F3	L19
IO46NB3F3	M21
IO46PB3F3	L21
IO47NB3F3	N17
IO47PB3F3	M17
IO48NB3F3	N18
IO48PB3F3	N19
IO49NB3F3	N16
IO49PB3F3	M16
IO50NB3F3	N20
IO50PB3F3	M20
IO51NB3F3	P21
IO51PB3F3	N21

FG676	
AX500 Function	Pin Number
IO51NB2F4	L20
IO51PB2F4	L21
IO52NB2F5	K26
IO52PB2F5	J26
IO53NB2F5	L23
IO53PB2F5	L22
IO54NB2F5	L24
IO54PB2F5	K24
IO55NB2F5	M20
IO55PB2F5	M21
IO56NB2F5	L26
IO56PB2F5	L25
IO57NB2F5	M23
IO57PB2F5	M22
IO58NB2F5	M26
IO58PB2F5	M25
IO59NB2F5	N22
IO59PB2F5	N23
IO60NB2F5	N24
IO60PB2F5	M24
IO61NB2F5	N20
IO61PB2F5	N21
IO62NB2F5	P25
IO62PB2F5	N25
Bank 3	
IO63NB3F6	T26
IO63PB3F6	R26
IO64NB3F6	R24
IO64PB3F6	P24
IO65NB3F6	P20
IO65PB3F6	P21
IO66NB3F6	T25
IO66PB3F6	R25
IO67NB3F6	T23
IO67PB3F6	R23

FG676	
AX500 Function	Pin Number
IO68NB3F6	V26
IO68PB3F6	U26
IO69NB3F6	V25
IO69PB3F6	U25
IO70NB3F6	Y25
IO70PB3F6	W25
IO71NB3F6	W24
IO71PB3F6	V24
IO72NB3F6	V23
IO72PB3F6	U23
IO73NB3F6	T21
IO73PB3F6	T20
IO74NB3F7	AA26
IO74PB3F7	Y26
IO75NB3F7	AA24
IO75PB3F7	Y24
IO76NB3F7	Y23
IO76PB3F7	W23
IO77NB3F7	V21
IO77PB3F7	U21
IO78NB3F7	AB25
IO78PB3F7	AA25
IO79NB3F7	AC26
IO79PB3F7	AB26
IO80NB3F7	AC24
IO80PB3F7	AB24
IO81NB3F7	AB23
IO81PB3F7	AA23
IO82NB3F7	AA22
IO82PB3F7	Y22
IO83NB3F7	AE26
IO83PB3F7	AD26
Bank 4	
IO84NB4F8	AB21
IO84PB4F8	AA21

FG676	
AX500 Function	Pin Number
IO85NB4F8	AE23
IO85PB4F8	AE24
IO86NB4F8	AC21
IO86PB4F8	AC22
IO87NB4F8	AF22
IO87PB4F8	AF23
IO88NB4F8	AD22
IO88PB4F8	AD23
IO89NB4F8	AC19
IO89PB4F8	AC20
IO90NB4F8	AE21
IO90PB4F8	AE22
IO91NB4F8	AA17
IO91PB4F8	AA18
IO92NB4F8	AD20
IO92PB4F8	AD21
IO93NB4F8	AF20
IO93PB4F8	AF21
IO94NB4F9	AE19
IO94PB4F9	AE20
IO95NB4F9	AC17
IO95PB4F9	AC18
IO96NB4F9	AD18
IO96PB4F9	AD19
IO97NB4F9	AA16
IO97PB4F9	Y16
IO98NB4F9	AE17
IO98PB4F9	AE18
IO99NB4F9	AC16
IO99PB4F9	AB16
IO100NB4F9	AF17
IO100PB4F9	AF18
IO101NB4F9	AA15
IO101PB4F9	Y15
IO102NB4F9	AC15

FG676	
AX1000 Function	**Pin Number**
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	**Pin Number**
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	**Pin Number**
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

FG896	
AX2000 Function	Pin Number
IO245PB5F23	AG8
IO246NB5F23	AD8
IO246PB5F23	AD9
IO247NB5F23	AG7
IO247PB5F23	AH7
IO248NB5F23	AK5
IO249NB5F23	AJ5
IO249PB5F23	AJ6
IO250NB5F23	AC8
IO250PB5F23	AC9
IO251NB5F23	AH6
IO251PB5F23	AG6
IO252NB5F23	AF6
IO252PB5F23	AF7
IO253NB5F23	AG2
IO253PB5F23	AG1
IO254NB5F23	AE7
IO254PB5F23	AE8
IO255NB5F23	AG5
IO255PB5F23	AH5
IO256NB5F23	AJ4
IO256PB5F23	AK4
Bank 6	
IO257NB6F24	AE4
IO257PB6F24	AF4
IO258NB6F24	AB7
IO258PB6F24	AC7
IO259NB6F24	AD5
IO259PB6F24	AE5
IO260NB6F24	AF1
IO260PB6F24	AF2
IO261NB6F24	AF3
IO261PB6F24	AG3
IO262NB6F24	AC4
IO262PB6F24	AD4

FG896	
AX2000 Function	Pin Number
IO263NB6F24	AD3
IO263PB6F24	AE3
IO264NB6F24	AB6
IO264PB6F24	AC6
IO265NB6F24	AD1
IO265PB6F24	AE1
IO266NB6F24	AA8
IO266PB6F24	AB8
IO267NB6F25	AB5
IO267PB6F25	AC5
IO268NB6F25	AB3
IO268PB6F25	AC3
IO269NB6F25	AC2
IO269PB6F25	AD2
IO270NB6F25	Y7
IO270PB6F25	AA7
IO271NB6F25	AA4
IO271PB6F25	AB4
IO272NB6F25	Y6
IO272PB6F25	AA6
IO273NB6F25	AB1*
IO273PB6F25	AE2*
IO274NB6F25	W8
IO274PB6F25	Y8
IO275NB6F25	Y5
IO275PB6F25	AA5
IO277NB6F25	AA2
IO277PB6F25	AA1
IO278NB6F26	W6
IO278PB6F26	W7
IO279NB6F26	Y3
IO279PB6F26	Y4
IO280NB6F26	V8
IO280PB6F26	V9
IO281NB6F26	Y1

FG896	
AX2000 Function	Pin Number
IO281PB6F26	Y2
IO282NB6F26	V5
IO282PB6F26	W5
IO284NB6F26	V7
IO284PB6F26	V6
IO285NB6F26	W3
IO285PB6F26	W4
IO286NB6F26	U8
IO286PB6F26	U9
IO287NB6F26	W1
IO287PB6F26	W2
IO288NB6F26	U7
IO288PB6F26	U6
IO290NB6F27	U4
IO290PB6F27	V4
IO291NB6F27	U3
IO291PB6F27	V3
IO292NB6F27	T5
IO292PB6F27	U5
IO293NB6F27	U2
IO293PB6F27	V2
IO294NB6F27	T8
IO294PB6F27	T9
IO296NB6F27	T1
IO296PB6F27	U1
IO298NB6F27	T7
IO298PB6F27	T6
IO299NB6F27	R2
IO299PB6F27	T2
Bank 7	
IO300NB7F28	R8
IO300PB7F28	R9
IO302NB7F28	R4
IO302PB7F28	R5
IO303NB7F28	P1

FG896	
AX2000 Function	Pin Number
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10

FG896	
AX2000 Function	Pin Number
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

CQ208	
AX250 Function	Pin Number
IO110PB7F7	19
IO112NB7F7	16
IO112PB7F7	17
IO117NB7F7	12
IO117PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121PB7F7	7
IO122NB7F7	5
IO122PB7F7	6
IO123NB7F7	3
IO123PB7F7	4
Dedicated I/O	
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90
GND	94
GND	99
GND	104
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169
GND	173

CQ208	
AX250 Function	Pin Number
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCDA	1
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
VCCIB0	193

CQ208	
AX250 Function	Pin Number
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCCPLA	189
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ256	
AX2000 Function	Pin Number
Bank 0	
IO01NB0F0	248
IO01PB0F0	249
IO04NB0F0	246
IO04PB0F0	247
IO05NB0F0	242
IO05PB0F0	243
IO08NB0F0	240
IO08PB0F0	241
Bank 0	
IO37NB0F3	234
IO37PB0F3	235
IO41NB0F3/HCLKAN	232
IO41PB0F3/HCLKAP	233
IO42NB0F3/HCLKBN	228
IO42PB0F3/HCLKBP	229
Bank 1 -	
IO43NB1F4/HCLKCN	220
IO43PB1F4/HCLKCP	221
IO44NB1F4/HCLKDN	216
IO44PB1F4/HCLKDP	217
Bank 1	
IO65NB1F6	210
IO65PB1F6	211
IO69NB1F6	208
IO69PB1F6	209
IO70NB1F6	199
IO71NB1F6	204
IO71PB1F6	205
IO73NB1F6	202
IO73PB1F6	203
IO74NB1F6	197
IO74PB1F6	198
Bank 2	
IO87NB2F8	187

CQ256	
AX2000 Function	Pin Number
IO87PB2F8	188
IO89PB2F8	186
Bank 2	
IO107NB2F10	184
IO107PB2F10	185
IO110NB2F10	180
IO110PB2F10	181
IO111NB2F10	178
IO111PB2F10	179
IO112NB2F10	174
IO112PB2F10	175
IO113NB2F10	172
IO113PB2F10	173
IO114NB2F10	168
IO114PB2F10	169
IO115NB2F10	166
IO115PB2F10	167
IO117NB2F10	162
IO117PB2F10	163
Bank 3	
IO139NB3F13	158
IO139PB3F13	159
IO141NB3F13	154
IO141PB3F13	155
IO142NB3F13	152
IO142PB3F13	153
IO145NB3F13	148
IO145PB3F13	149
IO146NB3F13	146
IO146PB3F13	147
IO147NB3F13	140
IO147PB3F13	141
IO148NB3F13	142
IO148PB3F13	143
IO149NB3F13	136

CQ256	
AX2000 Function	Pin Number
IO149PB3F13	137
Bank 3	
IO165NB3F15	135
IO167NB3F15	133
IO167PB3F15	134
Bank 4	
IO181NB4F17	124
IO181PB4F17	125
IO182NB4F17	122
IO182PB4F17	123
IO183NB4F17	118
IO183PB4F17	119
IO184NB4F17	116
IO184PB4F17	117
IO190NB4F17	112
IO190PB4F17	113
IO192NB4F17	110
IO192PB4F17	111
Bank 4	
IO212NB4F19/CLKEN	104
IO212PB4F19/CLKEP	105
IO213NB4F19/CLKFN	100
IO213PB4F19/CLKFP	101
Bank 5	
IO214NB5F20/CLKGN	92
IO214PB5F20/CLKGP	93
IO215NB5F20/CLKHN	88
IO215PB5F20/CLKHP	89
Bank 5	
IO236NB5F22	82
IO236PB5F22	83
IO238NB5F22	80
IO238PB5F22	81
IO240NB5F22	76
IO240PB5F22	77

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "Axcelerator Family Device Status" table on page iii, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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